

General Description

The Sanrise SRC65R800 is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R800 break down voltage is 650V and it has a high rugged avalanche characteristic.

The SRC65R800 is available in TO-220F, TO-252 packages.

Features

- Ultra Low $R_{DS(ON)} = 800m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 6.2nC$ typ.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

Application

- LED lighting
- Quick Charger

Symbol

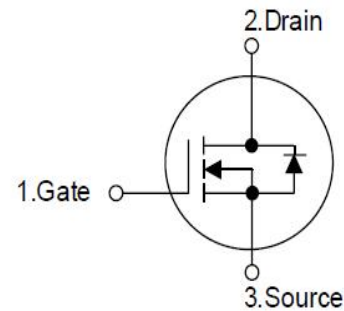


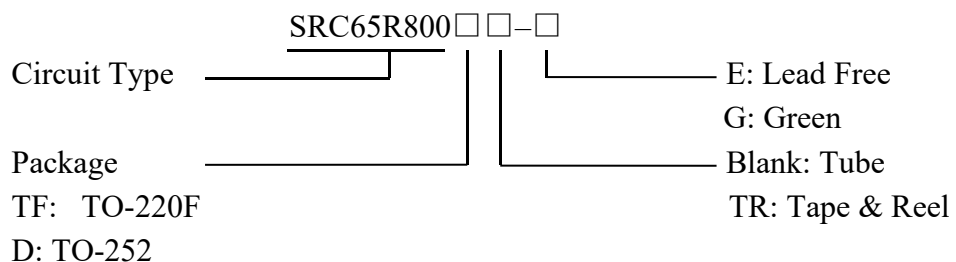
Figure 1 Symbol of SRC65R800

Package Type



Figure 2 Package Types of SRC65R800

Ordering Information



Package	Part Number	Marking ID	Packing Type
TO-220F	SRC65R800TF-G	SRC65R800TFG	Tube
TO-252	SRC65R800DTR-G	SRC65R800DGG	Tape & Reel

Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage (static)		V_{GSS}	±20	V
Gate-Source Voltage (dynamic), AC ($f > 1$ Hz)		V_{GSS}	±30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	3.9	A
			2.5	
	$T_C = 125^\circ\text{C}$		1.8	
Power Dissipation ($T_C = 25^\circ\text{C}, TO-220F$)		P_{tot}	20	W
Power Dissipation ($T_C = 25^\circ\text{C}, TO-252$)		P_{tot}	29	W
Pulsed Drain Current (Note 2)		I_{DM}	11.7	A
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	80	mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.1	mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	0.2	A
Continuous Diode Forward Current		I_S	3.9	A
Diode Pulse Current		$I_{S,PULSE}$	11.7	A
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480V$		dv/dt	15	V/ns
Reverse Diode dv/dt , $V_{DS} \leq 480V$, $I_{SD} \leq I_D$		dv/dt	50	V/ns
Operating Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 to 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 3.0A$, $V_{DD} = 60V$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-220F	R_{thJC}			6.0	$^\circ\text{C} / \text{W}$
	TO-252				4.2	
Thermal resistance, Junction-to-Ambient	TO-220F	R_{thJA}			80	$^\circ\text{C} / \text{W}$
	TO-252				62	

Electrical Characteristics

$T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.8mA$	2.5	3.5	4.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1.5A$		0.67	0.8	Ω
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		6.0		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		293		pF
Output Capacitance	C_{OSS}			15		pF
Reverse Transfer Capacitance	C_{RSS}			0.4		
Effective output capacitance, energy related ^{NOTE5}	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 400V$		8.8		pF
Effective output capacitance, time related ^{NOTE6}	$C_{O(tr)}$			55.6		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=1.6A, R_G=10\Omega, V_{GS}=10V$		6		ns
Rise Time	t_r			5		
Turn-off Delay Time	$t_{d(off)}$			40		
Fall Time	t_f			13		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=480V, I_D=1.5A, V_{GS}=0 \text{ to } 10V$		1.5		nC
Gate to Drain Charge	Q_{gd}			2.2		
Gate Charge Total	Q_g			6.2		
Gate Plateau Voltage	$V_{plateau}$			5.0		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=1.5A$		0.82	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=100V, I_F=1.5A, dI_F/dt=100A/\mu s$		110		ns
Reverse Recovery Charge	Q_{rr}			0.45		μC
Peak Reverse Recovery Current	I_{rrm}			8.2		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 400V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 400V



Shenzhen Sanrise Technology Co., LTD

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